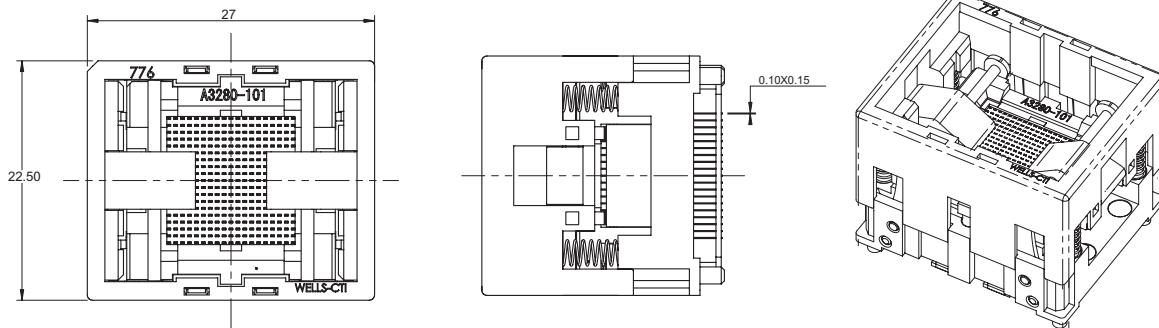


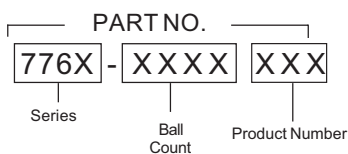
776 Series Open Top CSP Socket

- Low cost / high performance achieved through use of carrier loaded stamped contact
- "U" contact supports any type of solder ball shape and composition
- Compact outline and low actuation force achieved through use of advanced latching mechanism
- Economical customization and pin pitch expansion enabled by maximized component standardization



Pitch e (mm)	Ball Count	Package Size	Contact Matrix.	Ball Dia. (mm)	Ball Height (mm)	Ball Composition	Part Number
0.50	163	8X11	12X18	0.30	0.22	Pb-free	776B4163-101
0.65	154	8X10	11X14	0.30	0.20	Eutectic	776A3154-101
	209	14X14	20X20	0.35	0.185	Eutectic	776A3209-501
	260	13X13	18X18	0.40	0.33	Pb-free	776A3260-101
	280	13X13	19X19	0.30	0.20	Eutectic	776A3280-101
	336	14X14	20X20	0.35	0.185	Eutectic	776A3336-501

DESCRIPTION & ORDERING INFORMATION



MATERIALS & SPECIFICATIONS

- Socket Body: PES, PEI, LCP or Equivalent
- Contact: Beryllium Copper Alloy
- Contact Plating: Gold
- Contact Force: 10 grams for Eutectic Solder Ball
17 grams for lead-free Solder Ball
- Contact Resistance: 200 mΩ
- Temperature Rating: 150°C
- Durability: 10,000 cycles min.